

December 2007

# 74VHC393 **Dual 4-Bit Binary Counter**

#### **Features**

- High Speed: f<sub>MAX</sub> = 170MHz (Typ.) at T<sub>A</sub> = 25°C
- Low power dissipation:  $I_{CC} = 4\mu A$  (Max.) at  $T_A = 25$ °C
- High noise immunity: V<sub>NIH</sub> = V<sub>NIL</sub> = 28% V<sub>CC</sub> (Min.)
- Power down protection is provided on all inputs
- Pin and function compatible with 74HC393

### **General Description**

The VHC393 is an advanced high speed CMOS 4-bit Binary Counter fabricated with silicon gate CMOS technology. It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation. It contains two independent counter circuits in one package, so that counting or frequency division of 8 binary bits can be achieved with one IC. This device changes state on the negative going transition of the CLOCK pulse. The counter can be reset to "0"  $(Q_0-Q_3 = "L")$  by a HIGH at the CLEAR input regardless of other inputs.

An input protection circuit ensures that 0V to 7V can be applied to the input pins without regard to the supply voltage. This device can be used to interface 5V to 3V systems and two supply systems such as battery back up. This circuit prevents device destruction due to mismatched supply and input voltages.

### **Ordering Information**

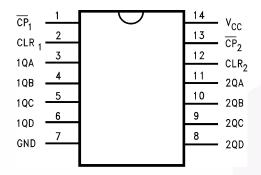
Order Number	Package Number	Package Description
74VHC393M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74VHC393SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74VHC393MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

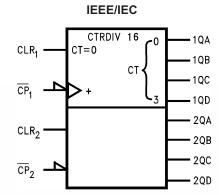


All packages are lead free per JEDEC: J-STD-020B standard.

## **Connection Diagram**



## Logic Symbol/s



## **Pin Descriptions**

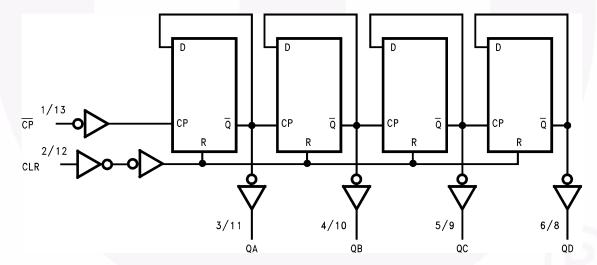
Pin Names	Description
CLR1, CLR2	Clear Inputs
$\overline{CP}_1, \overline{CP}_2$	Clock Pulse Inputs
QA, QB, QC, QD	Outputs

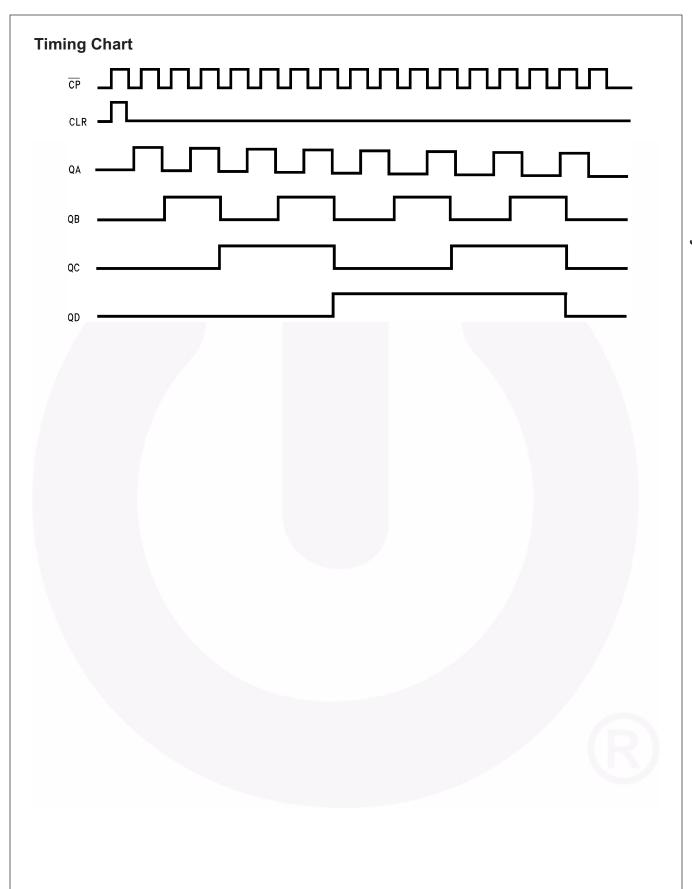
### **Truth Table**

Inpu		Out	puts		
CP	CLR	QA	QB	QC	QD
Х	Н	L	L	L	L
Ł	L		Cou	nt Up	
<u>_</u>	L		No C	hange	

X: Don't Care

## **System Diagram**





### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V <sub>CC</sub>	Supply Voltage	-0.5V to +7.0V
V <sub>IN</sub>	DC Input Voltage	-0.5V to +7.0V
V <sub>OUT</sub>	DC Output Voltage	–0.5V to V <sub>CC</sub> + 0.5V
I <sub>IK</sub>	Input Diode Current	–20mA
I <sub>OK</sub>	Output Diode Current <sup>(4)</sup>	±20mA
I <sub>OUT</sub>	DC Output Current	±25mA
I <sub>CC</sub>	DC V <sub>CC</sub> /GND Current	±75mA
T <sub>STG</sub>	Storage Temperature	−65°C to +150°C
T <sub>L</sub>	Lead Temperature (Soldering, 10 seconds)	260°C

## Recommended Operating Conditions<sup>(1)</sup>

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V <sub>CC</sub>	Supply Voltage	2.0V to +5.5V
V <sub>IN</sub>	Input Voltage	0V to +5.5V
V <sub>OUT</sub>	Output Voltage	0V to V <sub>CC</sub>
T <sub>OPR</sub>	Operating Temperature	-40°C to +85°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time	
	$V_{CC} = 3.3V \pm 0.3V$	0 ~ 100ns/V
	$V_{CC} = 5.0V \pm 0.5V$	0 ~ 20ns/V

#### Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

## **DC Electrical Characteristics**

					T	<sub>A</sub> = 25°	С		40°C to 5°C	
Symbol	Parameter	V <sub>CC</sub> (V)	Con	ditions	Min.	Тур.	Max.	Min.	Max.	Units
V <sub>IH</sub>	HIGH Level Input	2.0			1.50			1.50		V
	Voltage	3.0 – 5.5			0.7 x V <sub>CC</sub>			0.7 x V <sub>CC</sub>		
V <sub>IL</sub>	LOW Level Input	2.0					0.50		0.50	V
	Voltage	3.0 – 5.5					0.3 x V <sub>CC</sub>		0.3 x V <sub>CC</sub>	
V <sub>OH</sub>	HIGH Level Output	2.0		$I_{OH} = -50\mu A$	1.9	2.0		1.9		V
	Voltage	3.0	or V <sub>IL</sub>		2.9	3.0		2.9		
		4.5			4.4	4.5		4.4		
		3.0		$I_{OH} = -4mA$	2.58			2.48		V
		4.5		$I_{OH} = -8mA$	3.94			3.80		
V <sub>OL</sub>	LOW Level Output	2.0		$I_{OL} = 50 \mu A$		0.0	0.1		0.1	V
	Voltage	3.0	or V <sub>IL</sub>			0.0	0.1		0.1	
		4.5				0.0	0.1		0.1	
		3.0		I <sub>OL</sub> = 4mA			0.36		0.44	V
	y	4.5		$I_{OL} = 8mA$			0.36		0.44	
I <sub>IN</sub>	Input Leakage Current	0 – 5.5	V <sub>IN</sub> = 5.5\	or GND			±0.1		±1.0	μA
I <sub>CC</sub>	Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$	or GND			4.0		40.0	μA

### **AC Electrical Characteristics**

				1	T <sub>A</sub> = 25°	С		40°C to 5°C	
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min.	Тур.	Max.	Min.	Max.	Units
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay	3.3 ± 0.3	$C_L = 15pF$		8.6	13.2	1.0	15.5	ns
	Time (CP-QA)		$C_L = 50pF$		11.1	16.7	1.0	19.0	1
		5.0 ± 0.5	$C_L = 15pF$		5.8	8.5	1.0	10.0	7
			$C_L = 50pF$		7.3	10.5	1.0	12.0	7
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay	$3.3 \pm 0.3$	$C_L = 15pF$		10.2	15.8	1.0	18.5	ns
	Time (CP-QB)		$C_L = 50pF$		12.7	19.3	1.0	22.0	7
		5.0 ± 0.5	$C_L = 15pF$		6.8	9.8	1.0	11.5	7
			$C_L = 50pF$		8.3	11.8	1.0	13.5	7
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay	3.3 ± 0.3	$C_L = 15pF$		11.7	18.0	1.0	21.0	ns
	Time (CP-QC)		$C_L = 50pF$		14.2	21.5	1.0	24.5	7
		5.0 ± 0.5	$C_L = 15pF$		7.7	11.2	1.0	13.0	7
			$C_L = 50pF$		9.2	13.2	1.0	15.0	7
t <sub>PLH</sub> , t <sub>PHL</sub>	t <sub>PLH</sub> , t <sub>PHL</sub> Propagation Delay Time (CP-QD)	3.3 ± 0.3	$C_L = 15pF$		13.0	19.7	1.0	23.0	ns
			$C_L = 50pF$		15.5	23.2	1.0	26.5	
		5.0 ± 0.5	$C_L = 15pF$		8.5	12.5	1.0	14.5	
			$C_L = 50pF$		10.0	14.5	1.0	16.5	
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay	3.3 ± 0.3	$C_L = 15pF$		7.9	12.3	1.0	14.5	ns
	Time (CLR–Q <sub>n</sub> )		$C_L = 50pF$		10.4	15.8	1.0	18.0	
		5.0 ± 0.5	$C_L = 15pF$		5.4	8.1	1.0	9.5	
			$C_L = 50pF$		6.9	10.1	1.0	11.5	
f <sub>MAX</sub>	Maximum Clock	3.3 ± 0.3	$C_L = 15pF$	75	120		65		MHz
		$C_L = 50pF$	45	65		35			
		5.0 ± 0.5	C <sub>L</sub> = 15pF	125	170		105		
			C <sub>L</sub> = 50pF	85	115		75		
C <sub>IN</sub>	Input Capacitance		V <sub>CC</sub> = Open		4	10		10	pF
C <sub>PD</sub>	Power Dissipation Capacitance		(2)		23				pF

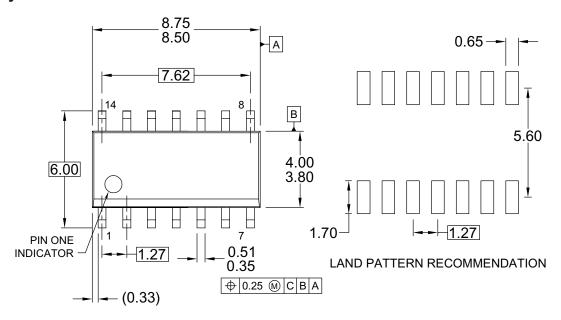
#### Note:

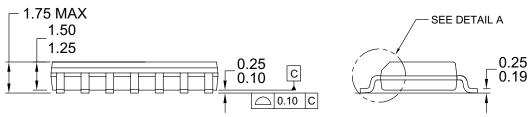
2. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load Average operating current can be obtained by the equation: I<sub>CC</sub>(Opr.) = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>IN</sub> + I<sub>CC</sub> / 2 (per Counter)

## **AC Operating Requirements**

			$T_A = 25^{\circ}C$		$T_A = -40$ °C to +85°C	
Symbol	Parameter	V <sub>CC</sub> (V)	Тур.	Guara	anteed Minimum	Units
$t_W(L), t_W(H)$	Minimum Pulse Width (CP)	$3.3 \pm 0.3$		5.0	5.0	ns
		5.0 ± 0.5		5.0	5.0	
t <sub>W</sub> (H)	Minimum Pulse Width (CLR)	$3.3 \pm 0.3$		5.0	5.0	ns
		5.0 ± 0.5		5.0	5.0	
t <sub>REM</sub>	Minimum Removal Time	$3.3 \pm 0.3$		5.0	5.0	ns
		5.0 ± 0.5		4.0	4.0	

## **Physical Dimensions**





NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X145-14M
- E) DRAWING CONFORMS TO ASME Y14.5M-1994
- F) DRAWING FILE NAME: M14AREV13

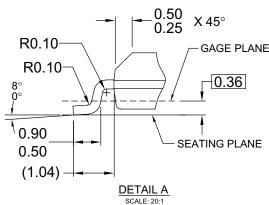


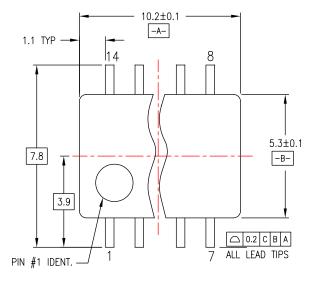
Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

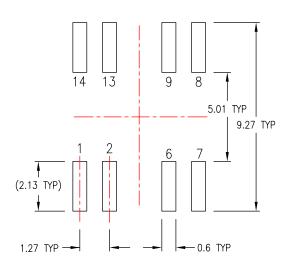
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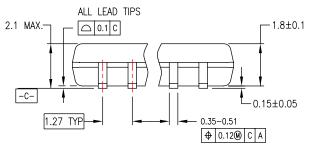
http://www.fairchildsemi.com/packaging/

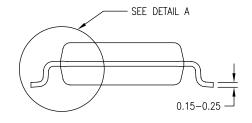
## Physical Dimensions (Continued)





#### LAND PATTERN RECOMMENDATION



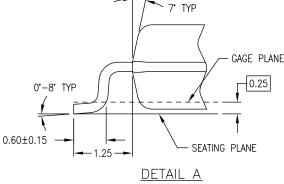


DIMENSIONS ARE IN MILLIMETERS

#### NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
  B. DIMENSIONS ARE IN MILLIMETERS.
  C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD

- FLASH, AND TIE BAR EXTRUSIONS.



M14DREVC

Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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### Physical Dimensions (Continued) 5.0±0.1 -A-0.65 0.43 TYP 6.4 4.4±0.1 -B-1.65 3.2 □ 0.2 C B A PIN #1 IDENT. 6.10 0.45 -LAND PATTERN RECOMMENDATION SEE DETAIL A ALL LEAD TIPS 0.90+0.15 1.2 MAX □ 0.1 C 0.09-0.20 -C-0.10±0.05 0.65 0.19 - 0.30 ⊕ 0.13M ABS CS 12.00°TOP & BOTTOM R0.09 min GAGE PLANE 0.25 0°-8° NOTES: 0.6±0.1 A. CONFORMS TO JEDEC REGISTRATION MO-153, SEATING PLANE R0.09min VARIATION AB, REF NOTE 6 1 00 **B. DIMENSIONS ARE IN MILLIMETERS DETAIL A** C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH,

- AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

Figure 3. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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